	Material Comp © Copyright 2005. I international and Par	osition Dec PC, Bannockb n-American co	c <b>laration</b> ourn, Illinois. A opyright conver	Il rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	ation o 1 encor	of the substances mpasses all lowe	within th r level ma	e manufactur aterials for wi	er listed i hich the n	tem. Note: nanufactur	: if the item is an as er has engineering	sembly with lowe responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type * Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier	· Information														
Company name* Compan				npany unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-03			
Contact Na	ame	Title - Contact				Phone - Contact*					Email - Contact*				
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorized	d Representative*	Title - Representative				Phone - Representative*				Email - Representative*					
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item   2SA2039						Effective Dat	ive Date Version Manufacturing Site		uring Site	Weight*		UOM	Unit Type	
							2024-05-03 CNG			326.16		mg	Each		
Aanufao	cturing Proccess Informa	tion					•								
	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-020		J-STD-020 MSI	L Rating	Peak Process Body		Body Temperature Max Time at Peak		Temperature Number		nber of Reflow Cyc	eles	
contains Bi			CU Alloy NA				0 C 30			seconds 3					
Comments															
or more i	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et							
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.33	mg	Supplier	Silicon (Si)	7440-21-3		0.33	mg
Die Attach Solder	0.15	mg	Supplier	Silver (Ag)	7440-22-4		0.0038	mg
			А	Lead (Pb)	7439-92-1	7a	0.1388	mg
			Supplier	Tin (Sn)	7440-31-5		0.0075	mg
lead Frame	191.37	mg	Supplier	Silver (Ag)	7440-22-4		0.3827	mg
			Supplier	Tin (Sn)	7440-31-5		0.2679	mg
			Supplier	Copper (Cu)	7440-50-8		190.7193	mg
Mold Compound-Black	130.34	mg		Brominated epoxy resin	proprietary data		1.8248	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		5.8653	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.1731	mg
			Supplier	Carbon Black (C)	1333-86-4		1.3034	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		97.755	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		22.1578	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2607	mg
Plating	3.34	mg	В	Bismuth (Bi)	7440-69-9		0.02	mg
			Supplier	Tin (Sn)	7440-31-5		3.32	mg
Wire Bond - Au	0.63	mg	Supplier	Gold (Au)	7440-57-5		0.63	mg